AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

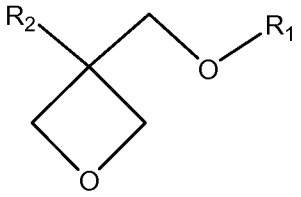
1. (Currently Amended): A radiation curable resin composition comprising:

a polyfunctional epoxy polymer (Component A) having a polybutadiene skeleton or a hydrogenated polybutadiene skeleton and two ~~or more~~ glycidyloxy groups at both terminals in the molecule;

an oxetane compound (Component B) represented by Formula (1) below and/or a compound in which an optionally branched alkyl group having 8 to 30 carbons has one epoxy group (Component C) having 8 to 30 carbons; and

a cationic photopolymerization initiator (Component X),

wherein a number of parts of Component A added is 25 to 45 parts by weight relative to 100 parts by weight of the total resin components



(1)

wherein R_1 denotes an optionally branched alkyl group having 6 to 30 carbons, or a phenyl group substituted with an alkyl group having 4 to 30 carbons, and R_2 denotes a hydrogen atom or an optionally branched alkyl group having 1 to 6 carbons,

wherein a polyfunctional epoxy compound other than Component A and/or a polyfunctional oxetane compound are not contained at 10 parts or greater relative to 100 parts of the total resin components.

2. (Canceled).

3. (Withdrawn): The radiation curable resin composition according to Claim 1, wherein the composition comprises a polymer having a glass transition temperature of -30°C or lower (Component D).

4. (Withdrawn): The radiation curable resin composition according to Claim 3, wherein the polymer (Component D) is a polybutadiene or polyisoprene to which 1 to 20 molecules of maleic anhydride are added per polymer molecule, or one obtained by ring-opening these acid anhydrides with an alcohol

5. (Previously Presented): The radiation curable resin composition according to any one of Claims 1 and 3-4, wherein the composition further comprises an antioxidant.

6. (Withdrawn): The radiation curable resin composition according to any one of Claims 1 to 4, wherein the composition further comprises an inorganic ion-exchanger.

7. (Withdrawn): The radiation curable resin composition according to any one of Claims 1 to 4, wherein the composition further comprises an antioxidant and an inorganic ion-exchanger.

8. (Previously Presented): A cured material formed by curing the radiation curable resin composition according to any one of Claims 1 and 3-4 by irradiation with actinic radiation.

9. (Original): A cured material formed by curing the radiation curable resin composition according to Claim 5 by irradiation with actinic radiation.

10. (Withdrawn): A cured material formed by curing the radiation curable resin composition according to Claim 6 by irradiation with actinic radiation.

11. (Withdrawn): A cured material formed by curing the radiation curable resin composition according to Claim 7 by irradiation with actinic radiation.

12. (Withdrawn): The cured material according to Claim 8, wherein the cured material has a storage modulus (G') of 1.2×10^5 Pa or less and a tan δ of 0.14 or less in a dynamic viscoelasticity measurement at 25°C and 1 Hz.

13. (Withdrawn): The cured material according to Claim 9, wherein the cured material has a storage modulus (G') of 1.2×10^5 Pa or less and a tan δ of 0.14 or less in a dynamic viscoelasticity measurement at 25°C and 1 Hz.

14. (Withdrawn): The cured material according to Claim 10, wherein the cured material has a storage modulus (G') of 1.2×10^5 Pa or less and a tan δ of 0.14 or less in a dynamic viscoelasticity measurement at 25°C and 1 Hz.

15. (Withdrawn): The cured material according to Claim 11, wherein the cured material has a storage modulus (G') of 1.2×10^5 Pa or less and a tan δ of 0.14 or less in a dynamic viscoelasticity measurement at 25°C and 1 Hz.

16. (New): The cured material according to Claim 8, wherein the cured material is formed on a vapor-deposited ITO film.

17. (New): The cured material according to Claim 8, wherein the cured material is formed on a vapor-deposited ITO film of a transparent touch panel.